

Wire bondable vertical Silicon Capacitor WBSC/WLSC 0202 10nF BV30



Rev. 4.11

General description

WBSC/WLSC Capacitors target power supplies decoupling and filtering of active devices. They are based on PICS Integrated Passive technology.

This product is a single 10nF capacitor in 0202 package size. Other capacitance values and other package sizes are available as a single die or capacitor array; please feel free to contact us.

WBSC/WLSC capacitors are directly mounted on the PCB application using die bonding and wire bonding processes. Standard FR4 PCB can be used. The bottom electrode is in TiNiAu and the top electrode is in TiWAu. Other top finishings such as Aluminum are available on request.

Key features

- Full compatible Monolithic ceramic capacitors for replacement
- Ultra-high stability of capacitance value:
 - Temperature 70ppm/K (-55 °C to +150 °C)
 - Voltage <0.02%/Volt
 - Negligible capacitance loss through ageing
- Low profile 0.25mm (standard), but lower thickness is possible (i.e 0.10mm) on request
- Small size 0.5 x 0.5 mm (0202 format)
- Break down voltage: 30V
- Low leakage current
- High reliability
- High operating temperature (up to 150 °C)
- Compatible with high temperature cycling during manufacturing operations (exceeding 300 °C)
- Compatible with EIA 0202 footprint
- Applicable for standard wire bonding assembly (ball and wedge)

Key applications

- Any demanding applications, such as medical, aerospace, industrial...
- Supply decoupling / filtering of active device
- High reliability applications
- Battery operated devices
- High temperature applications
- High volumetric efficiency (i.e. capacitance per unit volume)



Functional diagram

The next figure provides implementation set-up diagram.

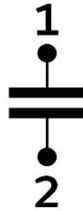


Figure 1 Block Diagram

Electrical performances

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
C	Capacitance value	@+25°C	-	10	-	nF
ΔC_P	Capacitance tolerance ⁽¹⁾	@+25°C	-15	-	+15	%
T _{OP}	Operating temperature ⁽²⁾		-55	-	150	°C
ΔC_T	Capacitance temperature variation	-55 °C to 150 °C	-	70	-	ppm/K
V _{DC}	Operating voltage ⁽³⁾		-	-	16 ⁽⁴⁾ 14.7 ⁽⁵⁾	V _{DC}
BV	Break down voltage	@+25°C	30	-	-	V
ΔC_{RVDC}	Capacitance voltage variation	From 0 V to V _{DC} , @+25°C	-	-	0.02	%/V _{DC}
IR	Insulation resistor	@V _{DC} , +25°C, 120s	-	10	-	GΩ
ESL	Equivalent Serial Inductance	@+25°C, SRF shunt mode	-	3	-	pH
ESD	HBM stress ⁽⁶⁾	JS-001-2017	2	-	-	kV

Table 1 - Electrical performances

- (1) other tolerance available upon request
(2) Regarding the storage temperature, please refer to the following application note.: [Storage and shelf life conditions](#)
(3) Lifetime is voltage and temperature dependent, please refer to application note 'Lifetime of 3D capacitors'
(4) 10 years of intrinsic lifetime prediction at 100°C continuous operation
(5) 10 years of intrinsic lifetime prediction at 150°C continuous operation
(6) please refer to application note 'ESD Challenge in 3D Murata Integrated Passive technology'

For extended frequency range (up to 26GHz), see Ultra large band Wire bonding vertical Silicon Capacitor (UWSC).

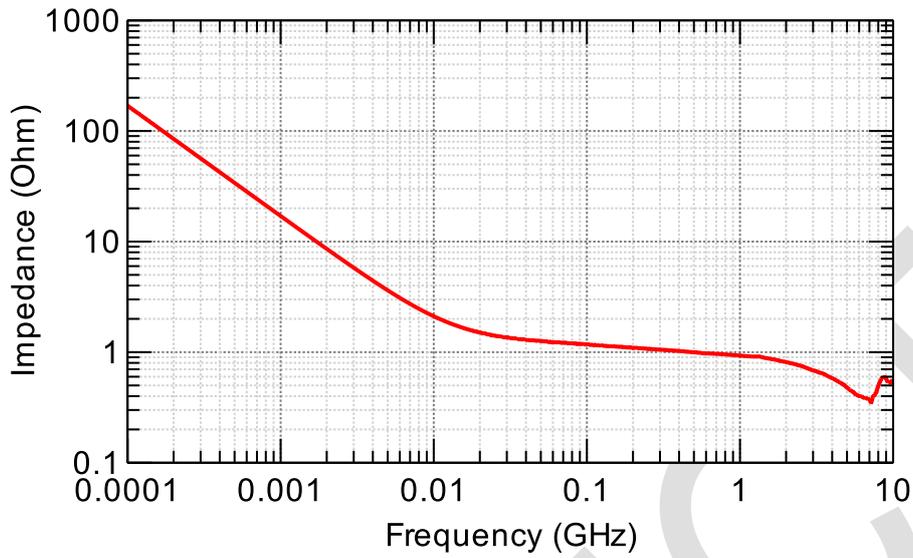


Figure 2 Impedance characteristic versus Frequency in shunt mode

Schematic of 10nF WLSC/WBSC in Shunt mode

Example of mounted 0202

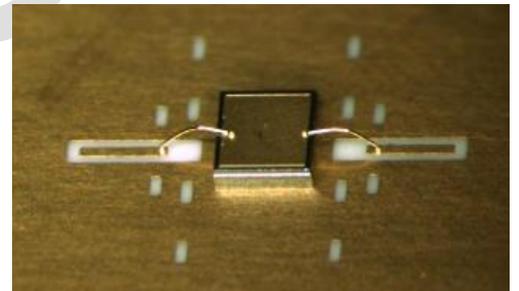
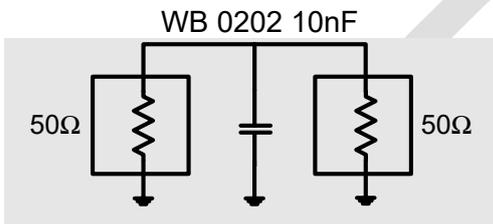


Figure 3 - 10nF WLSC/WBSC measurement schematic

Figure 4 – micro picture of mounted 0202 WLSC/WBSC



Pinning definition

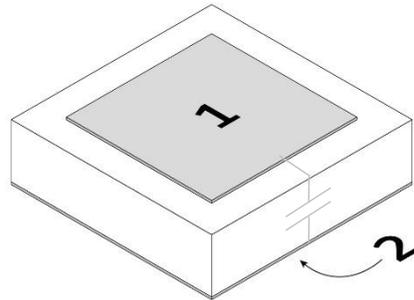


Figure 5 Pinning definition

pin #	Symbol	Coordinates X / Y
1	Signal	0.0 / 0.0
2	GND	Backside

Table 2 - Pinning description. Reference (0,0) located at the centre of the die.

Ordering Information

Type number	Package		
	Packaging	Finishing	Description
935142841510-F1T	6" FFC ⁽¹⁾	Au ⁽²⁾	WBSC 10nF/0202 – 1 bondpad – 0.50 x 0.50mm x 0.25mm ⁽³⁾
935142841510-F2T	8" FFC ⁽¹⁾	Au ⁽²⁾	WBSC 10nF/0202 – 1 bondpad – 0.50 x 0.50mm x 0.25mm ⁽³⁾
935142841510-E1T	6" expander grip	Au ⁽²⁾	WBSC 10nF/0202 – 1 bondpad – 0.50 x 0.50mm x 0.25mm ⁽³⁾
935142841510-T3T	T&R 1Kunits ⁽⁴⁾	Au ⁽²⁾	WBSC 10nF/0202 – 1 bondpad – 0.50 x 0.50mm x 0.25mm ⁽³⁾
935142841510-W0T	Waffle pack 400units	Au ⁽²⁾	WBSC 10nF/0202 – 1 bondpad – 0.50 x 0.50mm x 0.25mm ⁽³⁾
935146841510-F1T	6" FFC ⁽¹⁾	Au ⁽²⁾	WLSC 10nF/0202 – 1 bondpad – 0.50 x 0.50mm x 0.10mm ⁽³⁾
935146841510-F2T	8" FFC ⁽¹⁾	Au ⁽²⁾	WLSC 10nF/0202 – 1 bondpad – 0.50 x 0.50mm x 0.10mm ⁽³⁾
935146841510-E1T	6" expander grip	Au ⁽²⁾	WLSC 10nF/0202 – 1 bondpad – 0.50 x 0.50mm x 0.10mm ⁽³⁾
935146841510-T3T	T&R 1Kunits ⁽⁴⁾	Au ⁽²⁾	WLSC 10nF/0202 – 1 bondpad – 0.50 x 0.50mm x 0.10mm ⁽³⁾
935146841510-W0T	Waffle pack 400units	Au ⁽²⁾	WLSC 10nF/0202 – 1 bondpad – 0.50 x 0.50mm x 0.10mm ⁽³⁾

- (1) Other film frame carriers are possible on request
- (2) Au = TiWAu (0.3µm) / Au (3µm)
- (3) Refer to Figure 7
- (4) missing capacitors can reach 0.5%

Table 3 - Packaging and ordering information

Product Name	Die Name	Description
WBSC841.510	WR0202510	WBSC 10nF/0202/BV30 – 1 bondpad – 0.50 x 0.50mm x 0.25mm
WLSC841.510	WR0202510	WLSC 10nF/0202/BV30 – 1 bondpad – 0.50 x 0.50mm x 0.10mm

Table 4 - Die information



Pad Metallization

The wire bondable capacitor like WBSC / WLSC is delivered as standard with the bottom electrode in TiNiAu (Ti=0.1µm; Ni=0.3µm; Au=0.2µm) and top electrode in TiW Au (0.3µm) / Au (3µm).

Other Metallization, such as Thick Gold or Aluminum pads are possible on request.

Silicon dies are not sensitive to humidity, please refer to applications notes ‘Assembly Notes’ section ‘Handling precautions and storage’.

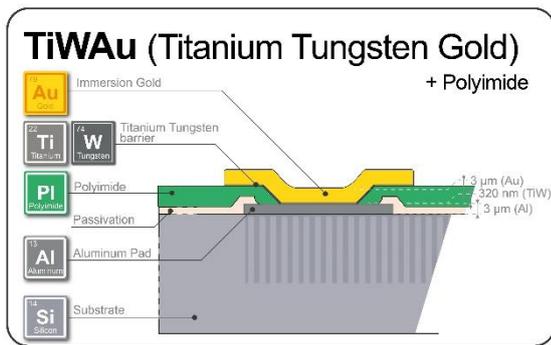


Figure 6 – Top electrode description

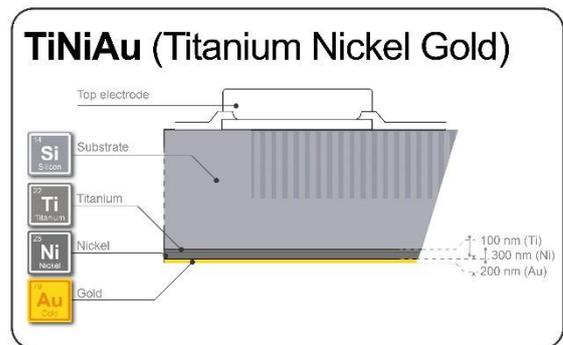


Figure 7 – Bottom electrode description

Material regulation

This product is RoHS compliant at the time of publication. For further information about regulation compliancy, please ask your sales representative.

Package outline

The product is delivered as a bare silicon die.

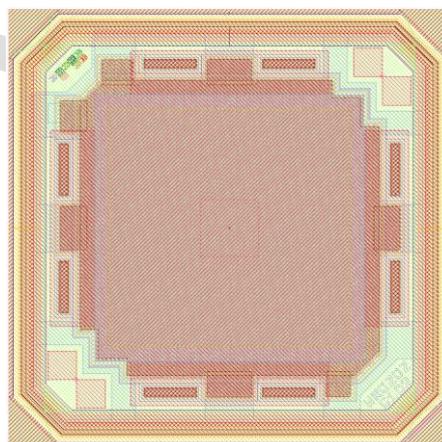


Figure 8 – Layout view



Al (mm)	Aw (mm)	B (mm)	d (mm)	e (mm)
0.50 ±0.03	0.50 ±0.03	0.25 or 0.10 ±0.015	0.406	0.406

Table 5 - Dimensions and tolerances

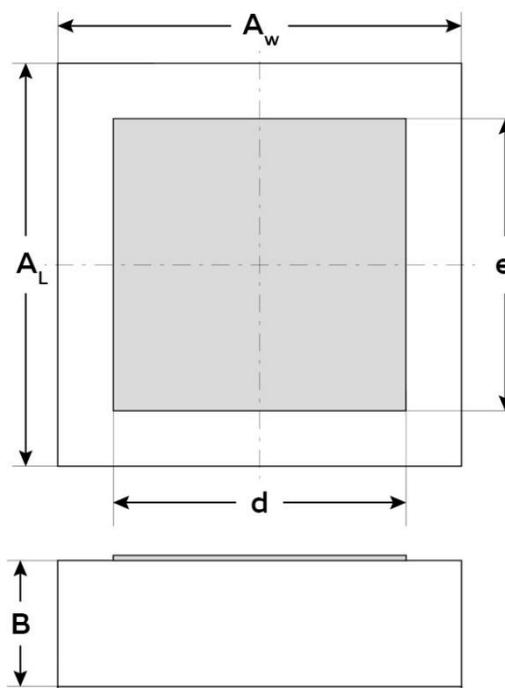


Figure 9 - Package outline 10nF Capacitor

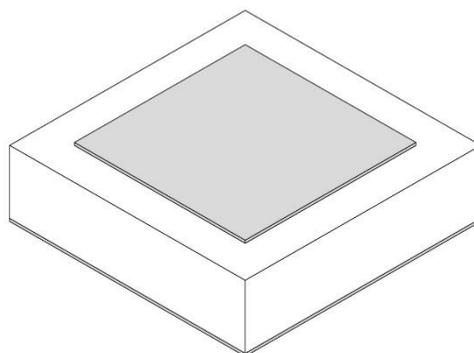


Figure 10 Package isometric view



Assembly

WBSC/WLSC capacitors are directly mounted on the PCB application using die bonding and wire bonding. It is applicable for standard wire bonding assembly (ball and wedge).

For further information, please see our mounting application note.

The attachment techniques recommended by Murata on the customer's substrates are fully detailed in specific documents available on our website. To assure the correct use and proper functioning of Murata capacitors **please download the assembly instructions on <https://www.murata.com/en-us/products/capacitor/siliconcapacitors> and read them carefully.**



Figure 11 Scan this QR Code to access the Murata Silicon Capacitor web page



Packaging format

Please refer to application note 'Products Storage Conditions and Shelf Life'.

Tape and Reel: Dies are flipped in the tape cavity (bump down) with die ID located near the driving holes of the tape.

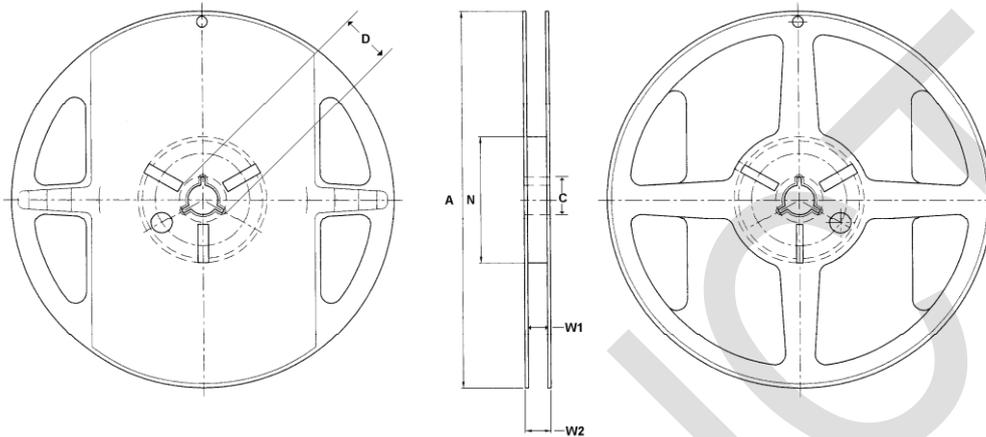


Figure 12 - Reel drawing

Tape Width	Diameter A	C	D	Hub N	W1	W2
8	178 (7 inches)	13.5	20.2	60	9	11.5

Table 6 – Reel dimensions (mm)

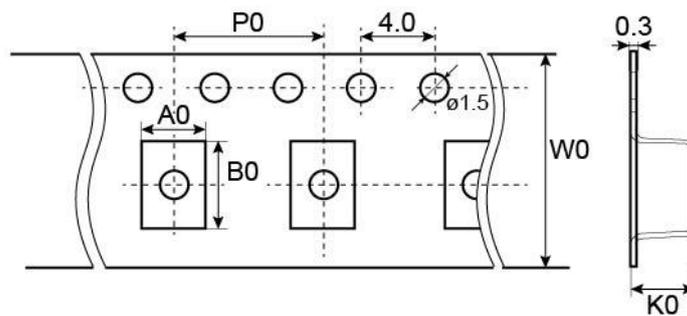


Figure 13 - Tape drawing

Cavity dimensions			Carrier tape width W0	Carrier tape pitch P0
Ao	Bo	Ko		
0.56	0.56	0.31	8 mm	4mm

Table 7 - Tape dimensions (mm)



Waffle pack:

Please refer to application note 'Waffle Pack Chip Carrier Handling & Opening Procedure'. Dies are not flipped in the waffle pack cavity (wire bond pad up).

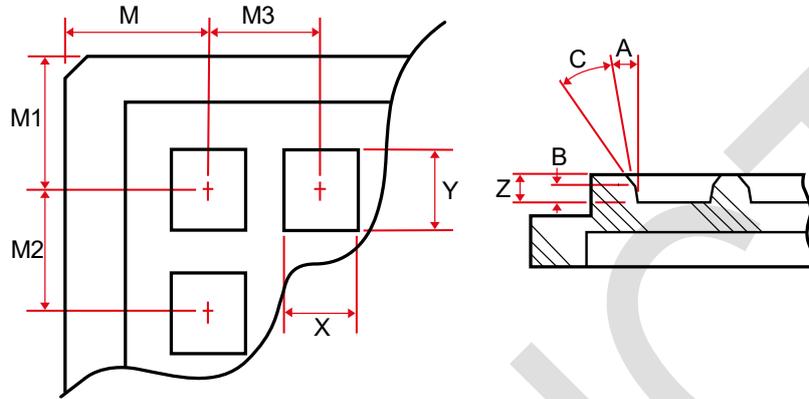


Table 8 - Waffle pack drawing

External dimensions	Max. capacity	Pocket length X	Pocket width Y	Pocket depth Z
2 inches	20 x 20	0.64 ±0.05	0.64 ±0.05	0.36 ±0.05

Table 9 - Waffle pack dimensions (mm) for 250µm thick product

M	M1	M2	M3	A
4.65 ±0.08	4.65 ±0.08	2.18 ±0.05	2.18 ±0.05	15° ±1/2°

Table 10 - Waffle pack dimensions (mm) for 250µm thick product

External dimensions	Max. capacity	Pocket length X	Pocket width Y	Pocket depth Z
2 inches	20 x 20	0.58 ±0.05	0.58 ±0.05	0.28 ±0.05

Table 11 - Waffle pack dimensions (mm) for 100µm thick product

M	M1	M2	M3	A
4.89 ±0.08	4.89 ±0.08	2.16 ±0.05	2.16 ±0.05	18° ±1/2°

Table 12 - Waffle pack dimensions (mm) for 100µm thick product



Film Frame Carrier:

With UV curable dicing tape (UV performed).

Good dies are identified using the SINF electronic mapping format. No ink is added on wafer to label other dies.

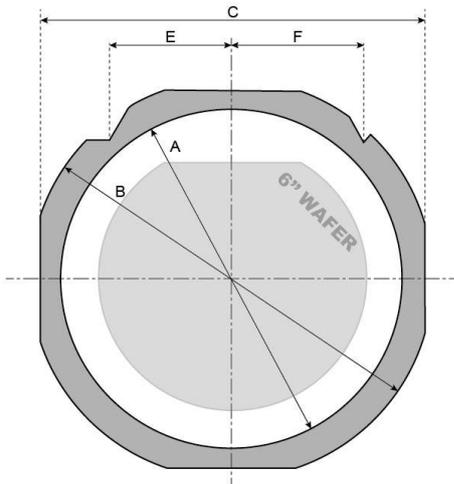


Figure 14 FF070 Frame with a 6" wafer

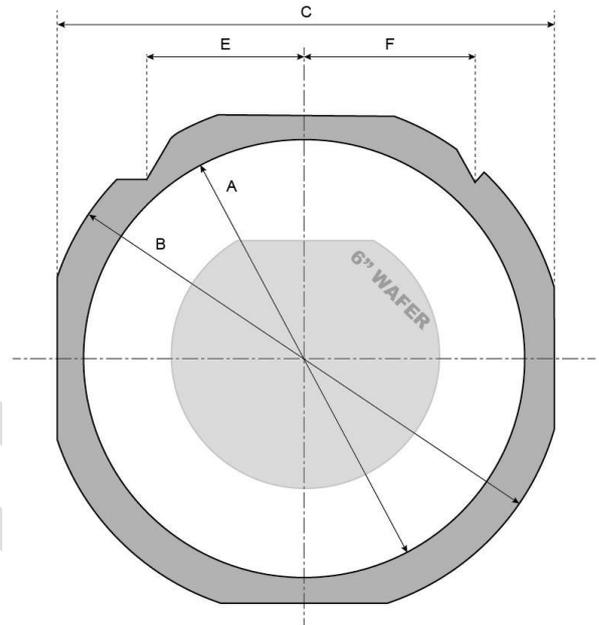


Figure 15 FF108 Frame with a 6" wafer

Frame Reference	Frame Style	Inside diameter A	Outside diameter B	Width C	Thickness	Pin location E	Pin location F
FF070 ⁽¹⁾	DTF-2-6-1	7.638"	8.976"	8.346"	0.048"	2.370"	2.5"
FF108 ⁽¹⁾	DTF-2-8-1	9.842"	11.653"	10.866"	0.048"	2.381"	2.5"

Table 13 - Frame dimensions (inches)

(1) or equivalent



Expander grip ring 6" diameter:

With UV curable dicing tape (UV performed)

Good dies are identified using the SINF electronic mapping format. No ink is added on wafer to label other dies.

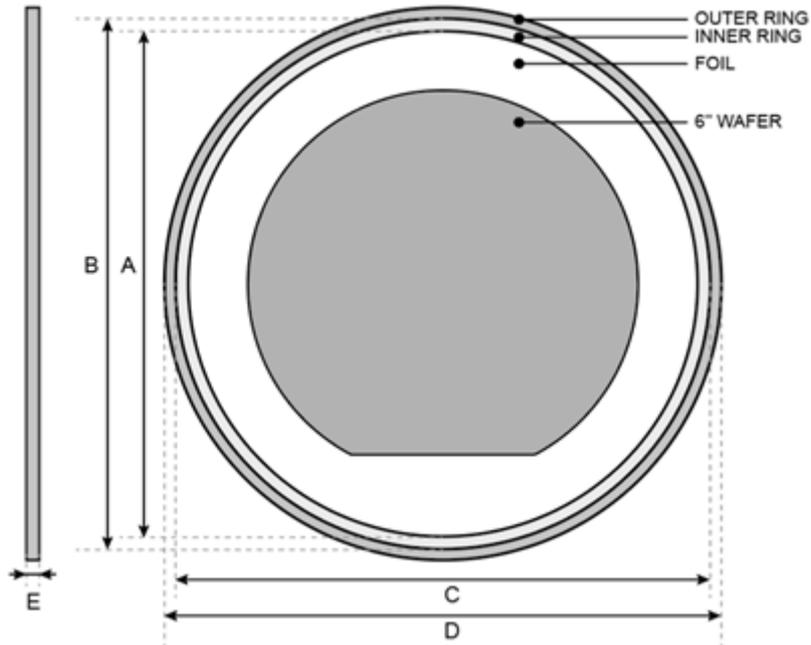


Figure 16 – Grip Ring drawing

Grip Ring Style	A	B	C	D	E	Locator Notch
GRP-2620-6 ⁽¹⁾	7.670"	7.973"	7.975"	8.280"	0.236"	None

Table 14 - Frame dimensions (inches)

(1) or equivalent

Definitions

Data sheet status

Objective specification: This data sheet contains target or goal specifications for product development.

Preliminary specification: This data sheet contains preliminary data; supplementary data may be published later.

Product specification: This data sheet contains final product specifications.

Limiting values

Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those given in the Electrical performances sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

Revision history

Revision	Date	Description	Author
Rev 1.00	2010 August 13 th	Creation	OGA
Rev 4.07	2021 April. 02 nd	Minor update	OGA, SCA, CGU, LLE
Rev 4.10	2023 May 31 st	Larger top metal pad with additional PI	OGA ; LIM
Rev 4.11	2025 Oct 22 nd	Typo update	OGA ; MOY

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